



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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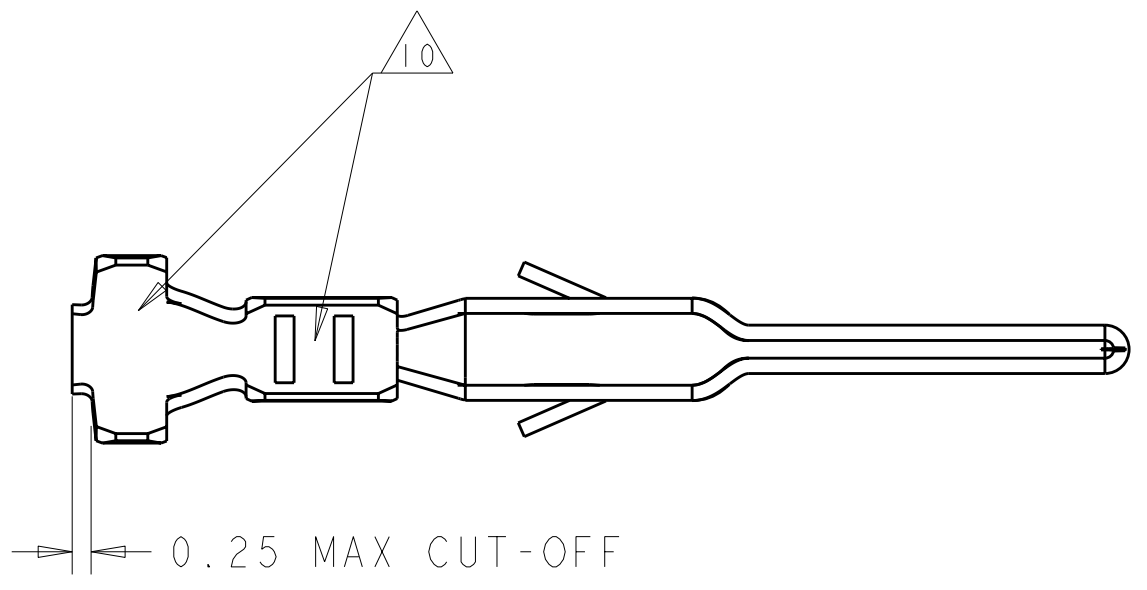
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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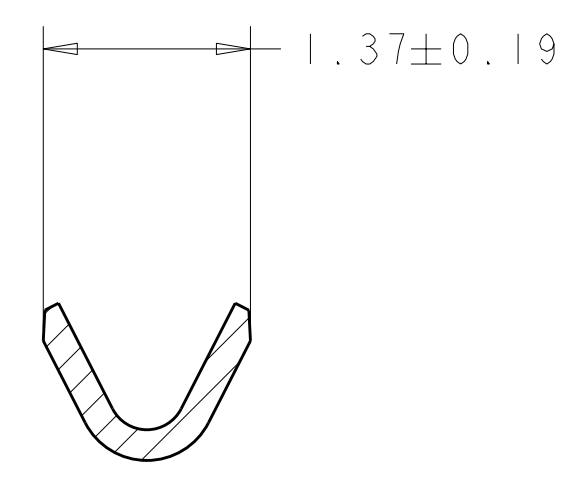
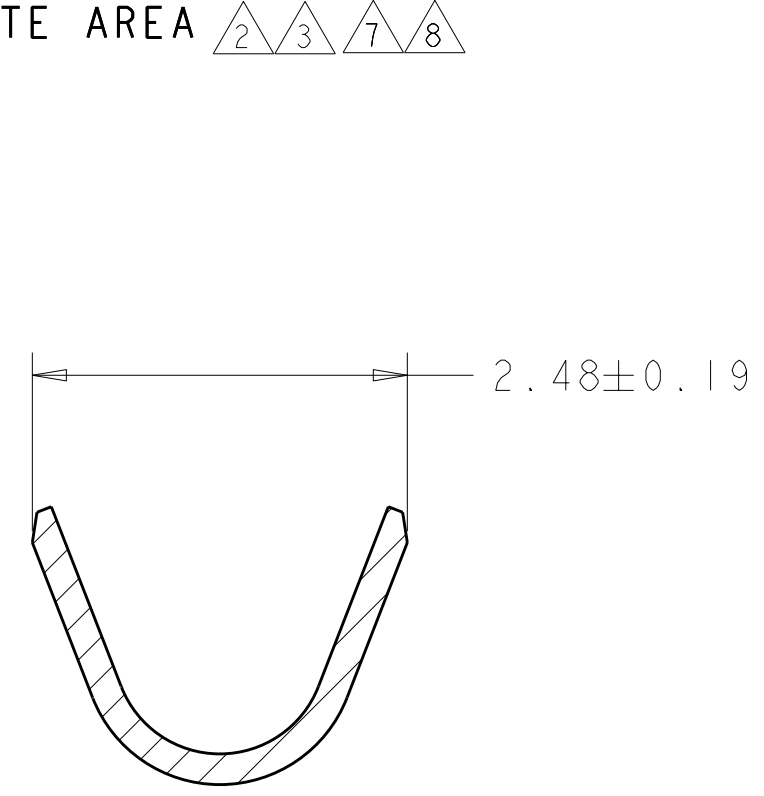
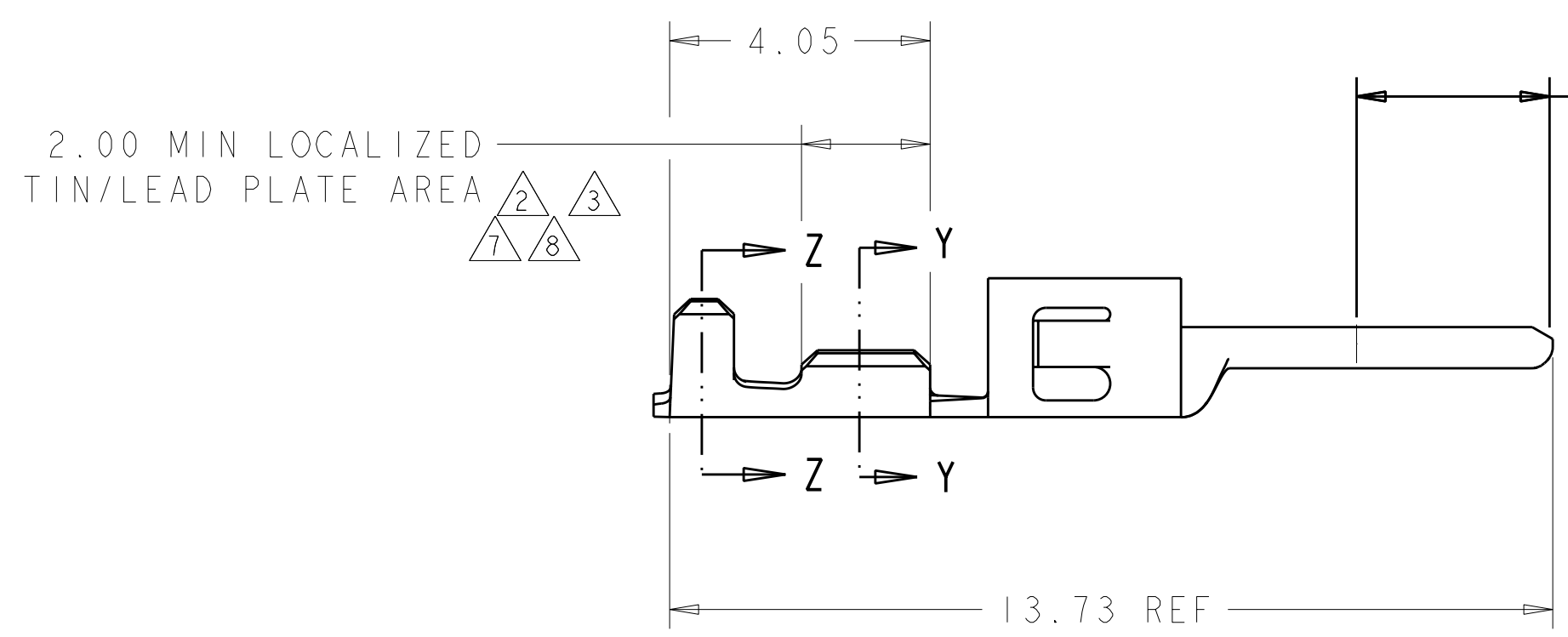


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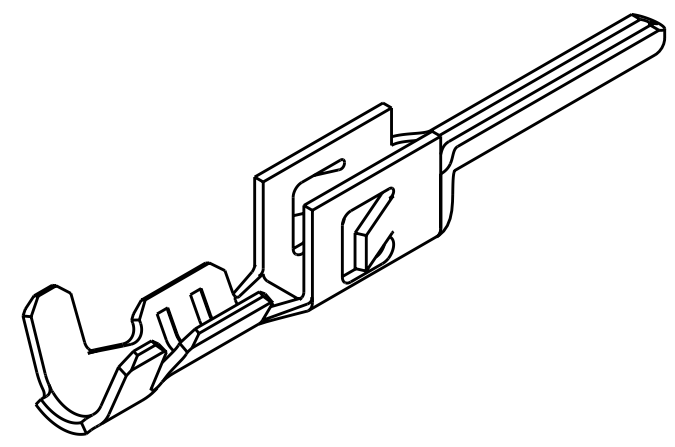
LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
CM	00	B2	REVISD PER ECO-11-005027	16MAR2011	RK	HMR	



- 1. 2.5 μm MIN BRIGHT TIN/LEAD ENTIRE STOCK OVER 1.27 μm MIN NICKEL ENTIRE STOCK.
- 2. 0.38 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.5 μm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27 μm MIN NICKEL ON ENTIRE STOCK.
- 3. 0.76 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.5 μm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27 μm MIN NICKEL ON ENTIRE STOCK.
- 4. WIRE RANGE 26-30 AWG.
- 5. INSULATION RANGE 0.89-1.52
- 6. 2.5 μm MIN BRIGHT TIN ENTIRE STOCK OVER 1.27 μm MIN NICKEL ENTIRE STOCK.
- 7. 0.38 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.5 μm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27 μm MIN NICKEL ON ENTIRE STOCK.
- 8. 0.76 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.5 μm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27 μm MIN NICKEL ON ENTIRE STOCK.
- 9. NOTE DELETED.
- 10. TIN PLATING THICKNESS INSIDE WIRE AND INSULATION BARRELS TO BE 1.27 μm MIN.



8	1-794613-2
7	1-794613-1
6	1-794613-0
3	794613-3
2	794613-2
1	794613-1
FINISH	PART NUMBER



METRIC

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DWN W J RUDY 29AUG2000	TE Connectivity
		CHK W DAVIS 29AUG2000	
		APVD W DAVIS 29AUG2000	
		PRODUCT SPEC	
MATERIAL: 0.20 THK BRASS		APPLICATION SPEC	NAME: PLUG CONTACT, CRIMP SNAP, 26-30 AWG, LOOSE PIECE, MICRO MATE-N-LOK(TM)
		WEIGHT	SIZE: A2
		CUSTOMER DRAWING	CAGE CODE: 00779
			DRAWING NO: 794613
			RESTRICTED TO: -
			SCALE: 10:1
			SHEET 1 OF 1
			REV: B2